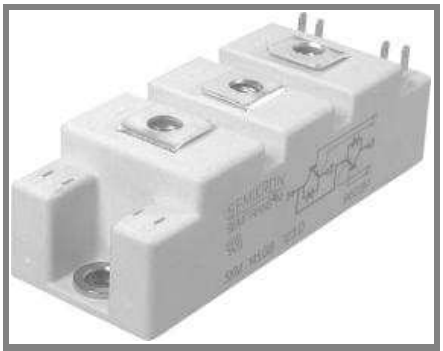
SKM 100GB063D



SEMITRANS® 2

Superfast NPT-IGBT Module

SKM 100GB063D

Features

- N channel, homogeneous Silicon structure (NPT- Non punch through IGBT)
- Low tail current with low temperature dependence
- High short circuit capability, self limiting if term. G is clamped to E
- Pos. temp.-coeff. of V_{CEsat}
- Very low C_{ies}, C_{oes}, C_{res}
- Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper Bonding Technology without hard mould
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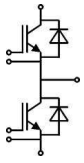
Typical Applications*

- Switching (not for linear use)
- Switched mode power supplies
- UPS
- Three phase inverters for servo / AC motor speed control
- Pulse frequencies also above 10 kHz

Absolute Maximum Ratings			T_c = 25 °C, unless otherwise specified	
Symbol	**Conditions**		**Values**	**Units**
IGBT				
V_{CES}	T_j = 25 °C		600	V
I_C	T_j = 150 °C	T_{case} = 25 °C	130	A
		T_{case} = 70 °C	100	A
I_{CRM}	I_{CRM}=2xI_{Cnom}		200	A
V_{GES}			± 20	V
t_{psc}	V_{CC} = 300 V; $V_{GE} \leq$ 20 V; V_{CES} < 600 V	T_j = 125 °C	10	µs
Inverse Diode				
I_F	T_j = 150 °C	T_{case} = 25 °C	100	A
		T_{case} = 80 °C	75	A
I_{FRM}	I_{FRM}=2xI_{Fnom}		200	A
I_{FSM}	t_p = 10 ms; sin.	T_j = 150 °C	720	A
Module				
$I_{t(RMS)}$			200	A
T_{vj}			- 40 ... + 150	°C
T_{stg}			- 40 ... + 125	°C
V_{isol}	AC, 1 min.		2500	V

Characteristics			T_c = 25 °C, unless otherwise specified			
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Units**
IGBT						
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 2 mA		4,5	5,5	6,5	V
I_{CES}	V_{GE} = 0 V, V_{CE} = V_{CES}	T_j = 25 °C		0,1	0,3	mA
V_{CE0}		T_j = 25 °C		1,05		V
		T_j = 125 °C		1		V
r_{CE}	V_{GE} = 15 V	T_j = 25°C		10,5		mΩ
		T_j = 125°C		14		mΩ
$V_{CE(sat)}$	I_{Cnom} = 100 A, V_{GE} = 15 V	T_j = 25°C$_{chiplev.}$		2,1	2,5	V
		T_j = 125°C$_{chiplev.}$		2,4	2,8	V
C_{ies}	V_{CE} = 25, V_{GE} = 0 V	f = 1 MHz		5,6		nF
C_{oes}				0,6		nF
C_{res}				0,4		nF
Q_G	V_{GE} = 0V - +15V			240		nC
R_{Gint}	T_j = °C			0		Ω
$t_{d(on)}$	R_{Gon} = 10 Ω	V_{CC} = 300V		50		ns
t_r		I_C= 100A		40		ns
E_{on}		T_j = 125 °C		4		mJ
$t_{d(off)}$	R_{Goff} = 10 Ω	V_{GE} = ±15 V		300		ns
t_f				35		ns
E_{off}				3		mJ
$R_{th(j-c)}$	per IGBT				0,27	K/W



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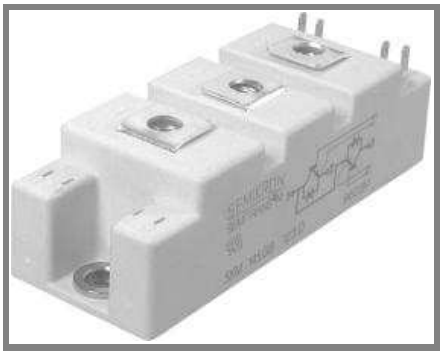

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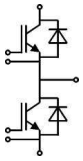

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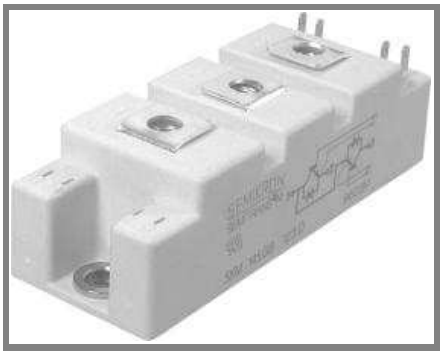
Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Units**
Inverse Diode						
$V_F = V_{EC}$	I_{Fnom} = 100 A; V_{GE} = 0 V	T_j = 25 °$C_{chiplev.}$		1,55	1,9	V
		T_j = 125 °$C_{chiplev.}$		1,55		V
V_{F0}		T_j = 125 °C			0,9	V
r_F		T_j = 125 °C		8	10	mΩ
I_{RRM}	I_F = 100 A	T_j = 125 °C		44		A
Q_{rr}				6		µC
E_{rr}	V_{GE} = -15 V; V_{CC} = 300 V					mJ
$R_{th(j-c)D}$	per diode				0,6	K/W
Module						
L_{CE}					30	nH
$R_{CC'+EE'}$	res., terminal-chip	T_{case}= 25 °C		0,75		mΩ
		T_{case}= 125 °C		1		mΩ
$R_{th(c-s)}$	per module				0,05	K/W
M_s	to heat sink M6		3		5	Nm
M_t	to terminals M5		2,5		5	Nm
w					160	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.



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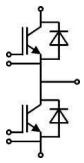

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Z_{th} Symbol	Conditions	Values	Units
$Z_{th(j-c)I}$			
R_i	i = 1	160	mk/W
R_i	i = 2	88	mk/W
R_i	i = 3	18	mk/W
R_i	i = 4	4	mk/W
tau_i	i = 1	0,0447	s
tau_i	i = 2	0,0087	s
tau_i	i = 3	0,0015	s
tau_i	i = 4	0,0002	s
$Z_{th(j-c)D}$			
R_i	i = 1	400	mk/W
R_i	i = 2	165	mk/W
R_i	i = 3	30,5	mk/W
R_i	i = 4	4,5	mk/W
tau_i	i = 1	0,0613	s
tau_i	i = 2	0,0085	s
tau_i	i = 3	0,0045	s
tau_i	i = 4	0,0003	s

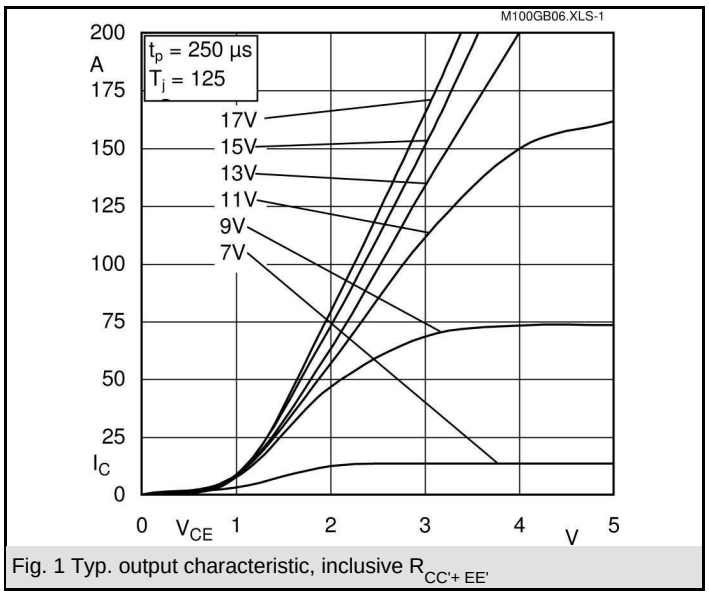

Fig. 1 Typ. output characteristic, inclusive $R_{CC'+EE'}$

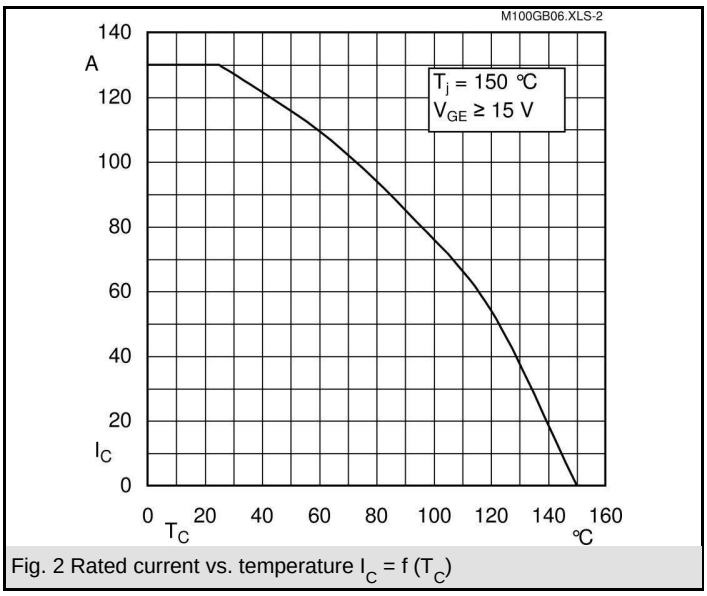

Fig. 2 Rated current vs. temperature $I_C = f(T_C)$

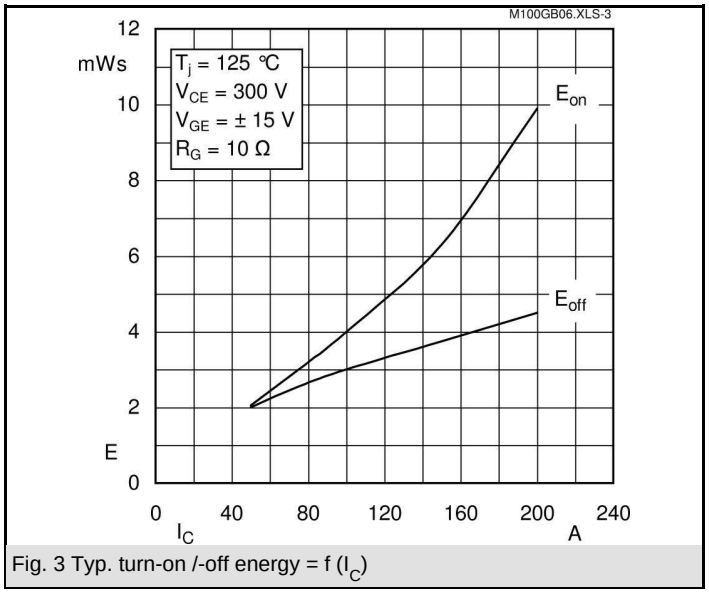

Fig. 3 Typ. turn-on /-off energy = f (I_C)

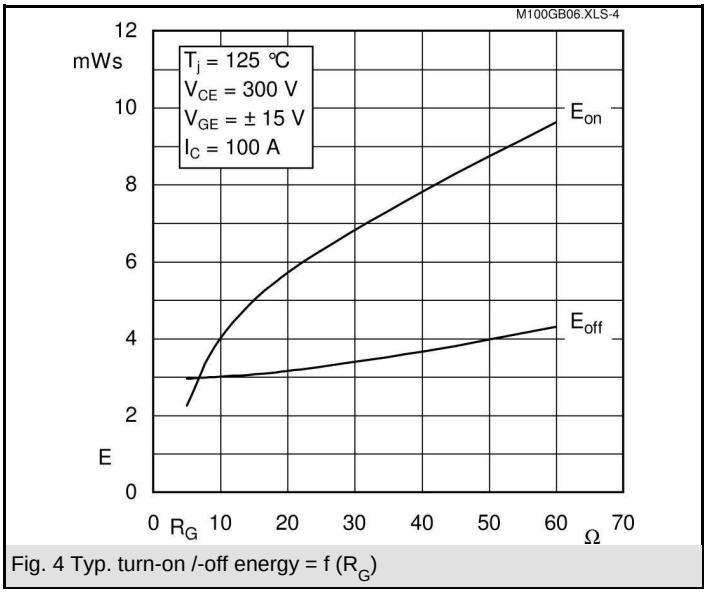

Fig. 4 Typ. turn-on /-off energy = f (R_G)

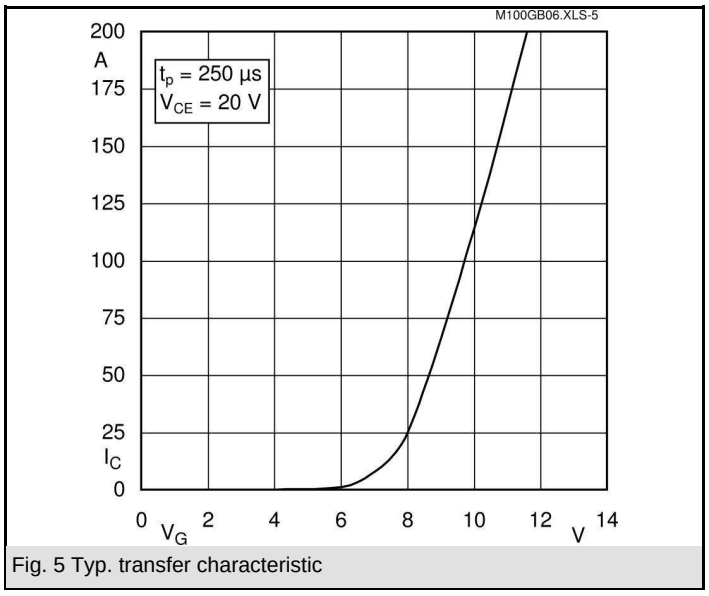

Fig. 5 Typ. transfer characteristic

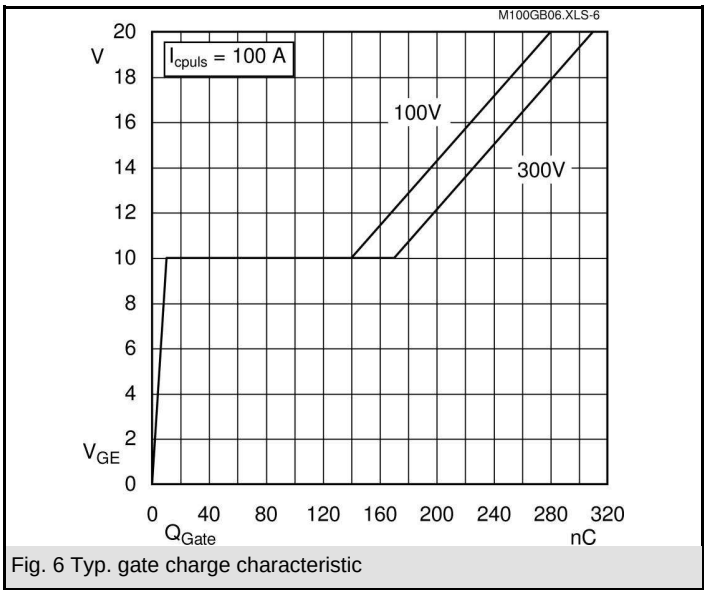

Fig. 6 Typ. gate charge characteristic

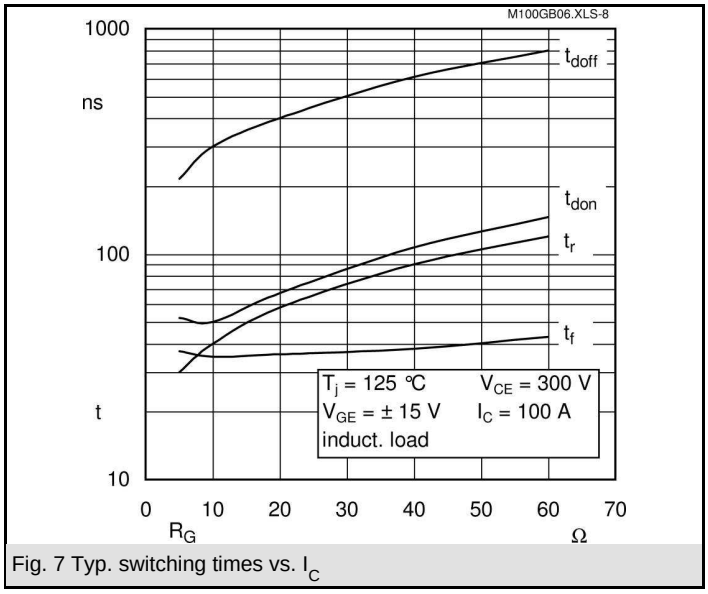

Fig. 7 Typ. switching times vs. I_C

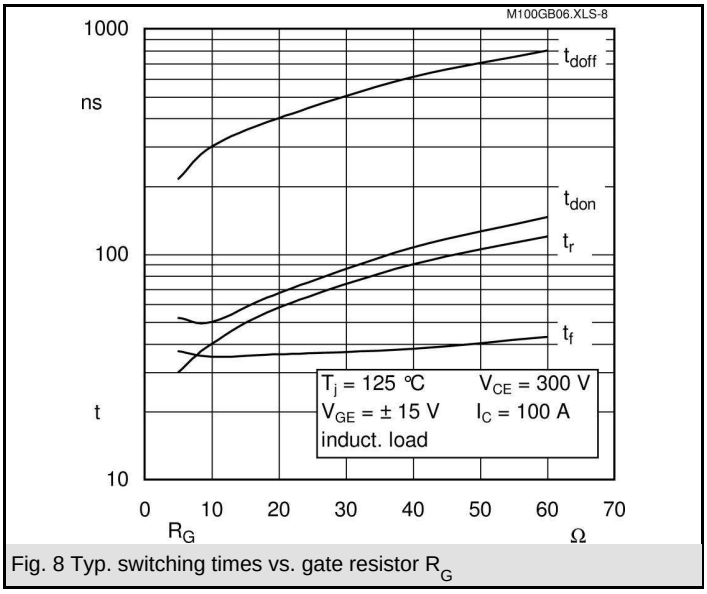

Fig. 8 Typ. switching times vs. gate resistor R_G

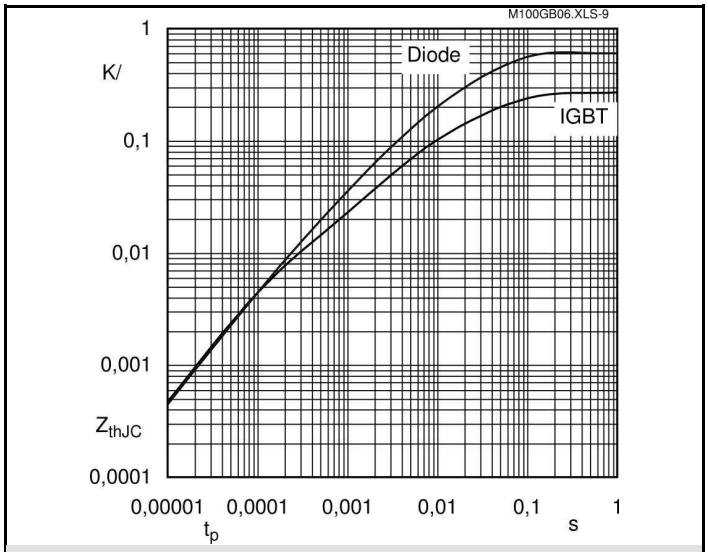

Fig. 9 Transient thermal impedance of IGBT and Diode

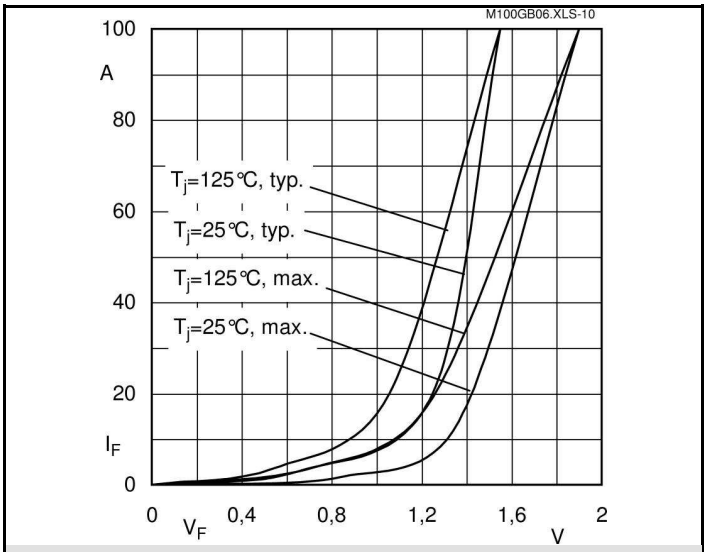

Fig. 10 CAL diode forward characteristic

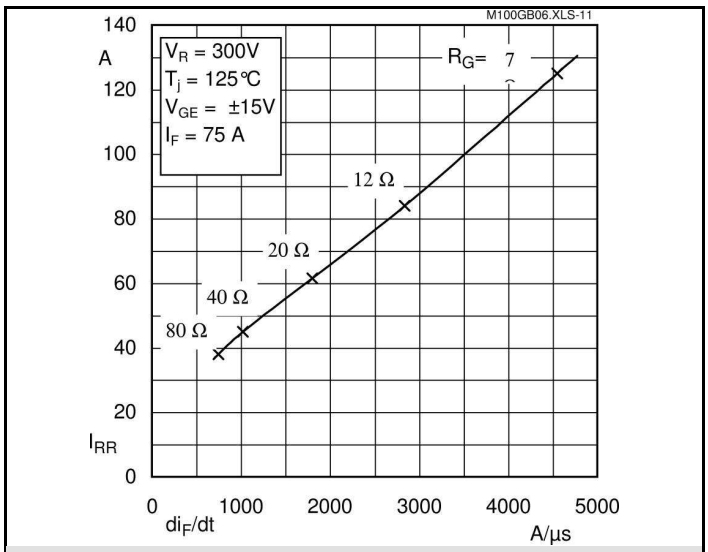

Fig. 11 Typ. CAL diode peak reverse recovery current

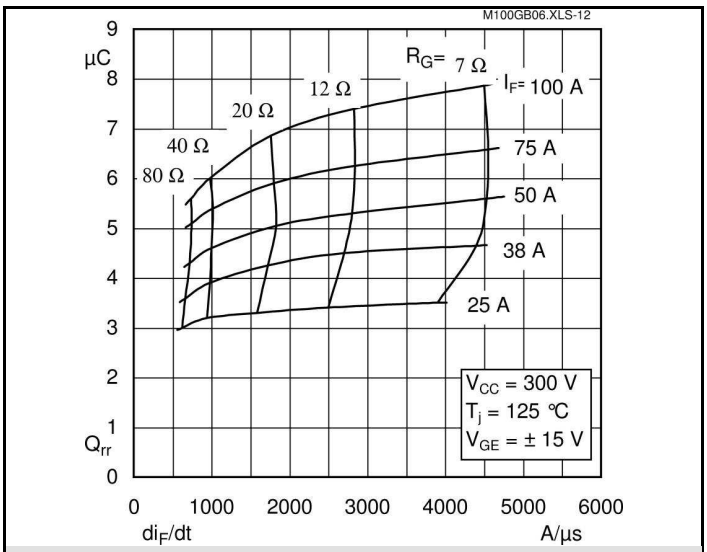

Fig. 12 Typ. CAL diode recovered charge

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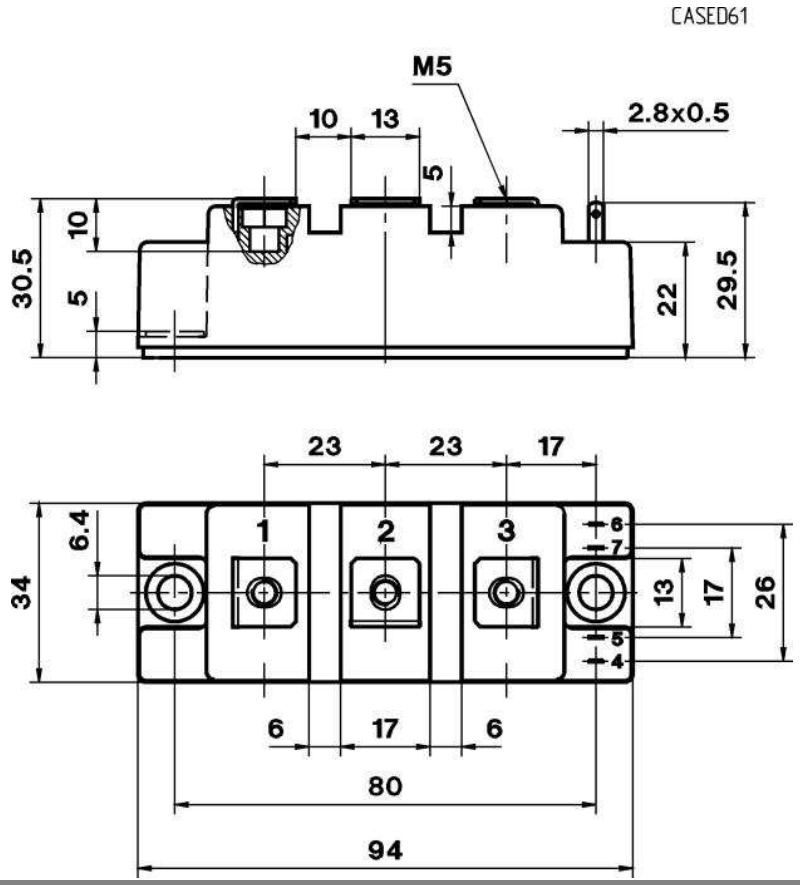
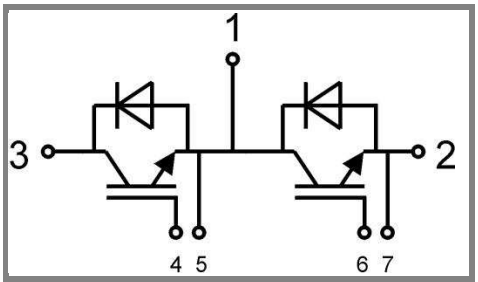
UL recognized file no. E 63 532



Case D 61



GB Case D 61

